



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Ball et al.

Serial No.: 09/854,759

Filed: May 14, 2001

For: USING BACKGRIND WAFER TAPE
TO ENABLE WAFER MOUNTING OF
BUMPED WAFERS

Confirmation No.: 8899

Examiner: J. Haran

Group Art Unit: 1733

Attorney Docket No.: 2269-4589US
(99-1151.00/US)

Notice of Allowance Mailed:

April 19, 2005

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EL 994845459 US

Date of Deposit with USPS: July 19, 2005

Person making Deposit: Steve Wong

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Specification begin on page 3 of this paper.

Serial No. 09/854,759

Amendments to the Claims are reflected in the listing of claims which begins on page 5 of this paper.

Remarks begin on page 16 of this paper.